

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Su TAO	01/12/2005
Yu-Fang TSAI	01/14/2005
RECEIVING PARTY DATA	
Name:	Advanced Semiconductor Engineering, Inc.
Street Address:	26 Chin 3rd Road, Nantze Export Processing Zone, Kaoshiung
City:	Kaoshiung
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11026763
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NAME OF SUBMITTER:	Harold V. Stotland
Total Attachments: 1 source=assignment_001#page1.tif	

CH \$40.00 11026763

USA Patent Appln.
Sole or Joint

CUSTOMER NO. 27717

ASSIGNMENT

In consideration of the sum of Ten Dollars (\$10.00) and other good and valuable consideration paid to each of the undersigned, to wit:

Insert Name(s)
of Inventor(s)

- (1) Su TAO (5) _____
 (2) Yu-Fang TSAI (6) _____
 (3) _____ (7) _____
 (4) _____ [] x box if continued on back

Insert Name
of Assignee
and Address

the receipt and sufficiency of which are hereby acknowledged by the undersigned who at the request of, hereby sell(s), assign(s) and transfer(s) unto:
ADVANCED SEMICONDUCTOR ENGINEERING, INC.
26 Chin 3rd Road, Nantze Export Processing Zone Kaoshiung, Kaoshiung,
Taiwan, R.O.C.
 (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in and to the invention known as

Title of
Invention

MULTI-CHIP PACKAGE STRUCTURE
filed on 31 December 2004; Serial number : 11/026,763

NOTE -> -> ->
(use only
when appln.
signed on
same date)

for which an application for Letters Patent of the United States of America has been executed even date herewith by the undersigned, and in and to any and all divisions, continuations, substitutes, and reissues thereof; and all resulting patents; and the undersigned hereby authorize(s) and request(s) the United States Commissioner or Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE'S full protection and title in and to the invention hereby transferred.

Please sign
concurrently
with Declaration

Signed on the date(s) indicated beside our signatures.

	INVENTOR(S)	DATE SIGNED	
1)	<u>Su TAO</u> Name: Su TAO	<u>Jan 12 '05</u>	
2)	<u>Yu-Fang Tsai</u> Name: Yu-Fang TSAI	<u>Jan 14 '05</u>	
3)	_____ Name:	_____	
4)	_____ Name:	_____	
5)	_____ Name:	_____	
6)	_____ Name:	_____	
7)	_____ Name:	_____	

FOR ADDITIONAL INVENTORS, check box [] and continue on opposite side
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(over)